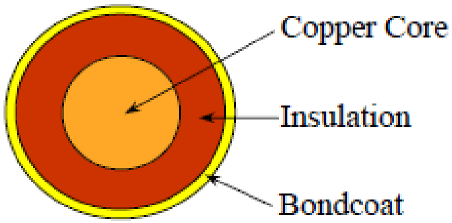
Contactless Card Wire (SC38-N-N)

Developed for the unique physical and performance demands of Smart Card manufacturing.



Core Diameter	0.0040 +/- 0.0001 inch, 0.1016 +/- 0.0025 mm
Insulation Thickness	Approximately 0.0009 inch, 0.0229 mm
Bondcoat Thickness	Approximately 0.0002 inch, 0.0050 mm
Overall	0.0052 +/- 0.0001 inch, 0.1321 +/- 0.0025 mm

Electrical:

D.C. Resistance	648 Ohms per 1,000 feet; 2,126 ohms per 1000 m
Dielectric Strength	No breakdown at 2000 volts D.C.
Insulation Resistance	5×10^{13} ohms at room temperature
Insulation Resistance	2.8×10^{9} ohms at 155 °C

Thermal:

Bonding Temperature	135-150 °C
Soldering Temperature	360-460 °C
Thermal Endurance	20,000 hour life at 160 °C

Mechanical:

Elongation	19%, Minimum
Tensile Strength	0.55 lbs. (250 gms), Minimum

Chemical:

Insulation	Modified Polyurethane. Resistant to exposure of 24 hours at room temperature to solvents including xylene, 50/50 cellosolve/xylene, perchloroethylene, 1% NaOH, 28% sulfuric acid and Freon TMS.
Bondcoat	Polyvinyl Butyral (PVB). Soluble in ethyl alcohol, methyl ethyl ketone (MEK) or acetone.

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